

**ORGANIC DIELECTRIC ELECTRONIC INTERCONNECT STRUCTURES
AND METHOD FOR MAKING**

ABSTRACT OF THE DISCLOSURE

A method for making a multi-layer electronic structure. A layer of dielectric material having a top surface and a bottom surface is provided. A layer of electrically conducting material is provided on one of the top surface and the bottom surface of the dielectric layer. At least one passage is formed through the dielectric layer to expose the layer of electrically conducting material. Electrically conducting material is deposited in at least one of the at least one passage through the dielectric layer. Portions of the layer of electrically conducting material are removed to define a pattern of circuitry. A stack is formed of plurality of structures including the layer of dielectric material and layer of electrically conducting material. The plurality of structures are aligned and joined together. Spaces between the structures are filled with electrically insulating material.